



Element distribution and phase constitution of $\text{Al}_2\text{O}_3\text{--TiC/W18Cr4V}$ vacuum diffusion bonded joint

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ABSTRACT

Vacuum diffusion bonding between $\text{Al}_2\text{O}_3\text{--TiC}$ ceramic composites and W18Cr4V tungsten-based tool alloy has been carried out by using Ti/Cu/Ti multi-interlayer. Element distribution near the $\text{Al}_2\text{O}_3\text{--TiC/W18Cr4V}$ interface was discussed and fracture morphology was analyzed using electron probe microanalysis. Additionally, phase constitutions of the $\text{Al}_2\text{O}_3\text{--TiC/W18Cr4V}$ joint were determined by X-ray diffraction. The results indicate that Ti-rich layers are formed near both $\text{Al}_2\text{O}_3\text{--TiC}$ and W18Cr4V. The Ti-rich layer near $\text{Al}_2\text{O}_3\text{--TiC}$ helps to wet the $\text{Al}_2\text{O}_3\text{--TiC}$ surface. The Ti-rich layer near W18Cr4V can restrain the formation of Fe–Ti intermetallic compounds in the diffusion transition zone. Residual Cu in the diffusion transition zone can act as a stress releasing zone. The structures of interfacial phases are identified as follows: $\text{Al}_2\text{O}_3\text{--TiC/TiO} + \text{Ti}_3\text{Al/Cu} + \text{CuTi/TiC}$ layer/mixed layer of $\text{Fe}_3\text{W}_3\text{C}$, Cr_{23}C_6 and $\alpha\text{-Fe/W18Cr4V}$. The fracture morphology of $\text{Al}_2\text{O}_3\text{--TiC/W18Cr4V}$ joint appears brittle features and the failure occurs within the $\text{Al}_2\text{O}_3\text{--TiC}$ ceramic.

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1. Introduction

$\text{Al}_2\text{O}_3\text{--TiC}$ ceramic composites have been widely used in the field of engineering with high strength and hardness, chemical stability and excellent wear resistance [1]. $\text{Al}_2\text{O}_3\text{--TiC}$ ceramic composites are frequently used to be one of the most suitable tool materials for machining hard materials [2]. Due to inherent brittleness of ceramics, $\text{Al}_2\text{O}_3\text{--TiC}$ presents poor machinability, which limits its extensive application. If the joining of $\text{Al}_2\text{O}_3\text{--TiC}$ ceramic composites and W18Cr4V tungsten-based tool alloy can be successfully realized, it will be important to expand the utilization of $\text{Al}_2\text{O}_3\text{--TiC}$ ceramic composites in machining industry.

Diffusion bonding process has been one of the technological tools to increase the use of ceramic materials. In order to form reliable diffusion bonded joint, a multi-interlayer is sandwiched between the components to be joined. Joining of $\text{Al}_2\text{O}_3\text{--TiC}$ ceramic composites with W18Cr4V tool alloy was investigated by using a Ti/Cu/Ti multi-interlayer. The Ti/Cu/Ti system was selected

for the following reasons: (1) Ti shows excellent behavior in promoting the wettability of Al_2O_3 as the most extensively studied active element [3,4]; (2) Cu can form a low-melting eutectic with Ti and the activity coefficient of Ti in Cu is close to unity. This high activity makes Ti attractive as the active element in Cu-based filler metals for joining ceramics [5]; (3) it has been well established that Al_2O_3 , when in contact with Cu–Ti alloys, develops strong chemical bonds at the interface [6].

In previous work, the residual stress distribution in $\text{Al}_2\text{O}_3\text{--TiC/W18Cr4V}$ diffusion bonded joints was calculated using finite element method (FEM) and preliminary study on the formation process of the transition zone and phase constitutions was also done [7–9]. However, details about the role of reaction layers are still largely unresolved issues. The objective of the present work is to begin to address some of these problems by reexamining element distribution and phase constitutions of the reaction layers formed during diffusion bonding of $\text{Al}_2\text{O}_3\text{--TiC}$ and W18Cr4V with a Ti/Cu/Ti multi-interlayer.

2. Experimental procedure

2.1. Equipment

The vacuum diffusion bonding equipment (Workhorse-II manufactured by Vacuum Industry Company) was used in the joining

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process. The main parameters of the equipment are: size of vacuum chamber $305 \times 305 \times 457 \text{ mm}^3$, heating power 45 kVA, highest heating temperature 1623 K, maximum pressure 30 tons applied through hydraulic pressure and maximum vacuum degree $1.5 \times 10^{-5} \text{ Pa}$. The vacuum system is composed of the mechanical pump and the diffusion pump.

2.2. Materials

Materials used are Al_2O_3 –TiC ceramic composites, W18Cr4 V tool alloy and Ti/Cu/Ti multi-interlayer. Al_2O_3 –TiC ceramic was made by hot pressure sintering (HPS) to a final circle plate having a dimension $\phi 52 \times 3.5 \text{ mm}^2$. The size of W18Cr4 V circle plate specimen is $\phi 52 \times 2 \text{ mm}^2$. Al_2O_3 –TiC ceramic consists of Al_2O_3 matrix with TiC particles. The chemical composition (wt%) of W18Cr4V alloy is: C 0.70–0.80%, Mn 0.10–0.40%, Si 0.20–0.40%, $S \leq 0.030\%$, $P \leq 0.030\%$, Cr 3.80–4.40%, V 1.00–1.40%, W 17.50–19.00%, Mo $\leq 0.30\%$ and Fe balance. A multi-interlayer of Ti/Cu/Ti (20 μm Ti/60 μm Cu/20 μm Ti) is employed to promote the joining between Al_2O_3 –TiC ceramic and W18Cr4V alloy and obtain tight metallurgic joint. Table 1 gives the chemical compositions and the thermo-physical properties of Ti and Cu.

2.3. Technology and preparing samples

Before diffusion bonding, the surfaces of materials to be bonded were prepared by conventional grinding and polishing techniques, resulting in a surface roughness R_a of 0.27–0.35 μm for the ceramic and 0.10–0.20 μm for both steel and interlayer. The faying surfaces were cleaned in acetone, followed by rinsing in distilled water and dried in air. After that, the diffusion bonding plates were overlapped (Fig. 1) and placed into vacuum chamber. Technological parameters used in the joining process were: the heating temperature $T = 1373$ – 1423 K , the pressure $P = 10$ – 15 MPa , the holding time $t = 45$ – 60 min and the vacuum degree of 1.33×10^{-4} – 10^{-5} Pa . The cooling process was conducted in the vacuum chamber that was cooled by circuit water. When the chamber temperature was cooled to 373 K, the Al_2O_3 –TiC/W18Cr4V diffusion bonded joints were taken out from the chamber.

A photo of the Al_2O_3 –TiC/W18Cr4V joint is shown in Fig. 2. The Al_2O_3 –TiC/W18Cr4V joints were cut into $12 \times 10 \times 9 \text{ mm}^3$ specimens (Fig. 1) perpendicular to the bonded interface by the line cutting machine. Microstructural morphology of the Al_2O_3 –TiC/W18Cr4V joint was analyzed by means of Nikon AFX-IIA metaloscope. Microhardness was measured via SHIMADZU micro-sclerometer. Element distribution near the Al_2O_3 –TiC/W18Cr4V interface, the fracture morphology and the composition on the fractured face were analyzed by JXA-8800R electron probe micro-analysis (EPMA). The reaction products were determined by D/MAX-RC XRD.

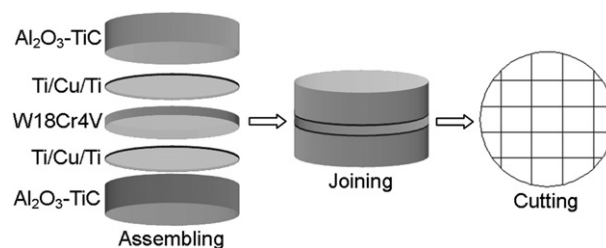


Fig. 1. Assembled and cut schematic diagram of specimen.

3. Results and discussion

3.1. Microstructural characteristics and element distribution

Microstructure near the interface of Al_2O_3 –TiC/W18Cr4V joint was observed by optical microscope (Fig. 3). The results indicate that a diffusion transition zone is formed between Al_2O_3 –TiC and W18Cr4V. Microstructural morphology of the diffusion transition zone is significantly different from that of the substrates, Al_2O_3 –TiC and W18Cr4V. The interface is straight at the Al_2O_3 –TiC side and zigzag at the W18Cr4V side.

Microhardness near the Al_2O_3 –TiC/W18Cr4V interface was measured via SHIMADZU micro-sclerometer with a load of 100 g and a load time of 10 s and the results are shown in Fig. 4.

It can be seen from Fig. 4 that the microhardness of diffusion transition zone is far lower than that of Al_2O_3 –TiC and slightly lower than that of W18Cr4V. Microhardness distribution, with a softer diffusion transition zone and two harder substrates, can provide sufficient ductility in the diffusion transition zone to avoid cracking.

Composition near the interface is the fundamental part of the joint in determining mechanical behavior. Distribution of alloy elements near the diffusion bonded Al_2O_3 –TiC/W18Cr4V interface was measured via EPMA. Fig. 5 presents a backscattered electron (BSE) image (Fig. 5a) and composition variation across the interface (Fig. 5b).

From Fig. 5a and b, it is evident that there are four different layers from Al_2O_3 –TiC to W18Cr4V in the diffusion transition zone: (1) a layer near Al_2O_3 –TiC, (2) wide central zone, (3) narrow black layer and (4) a layer near W18Cr4V. Fig. 5b shows that the layer near Al_2O_3 –TiC mainly contains Ti (22.4–91.7 wt%), Al (6.9–64.3 wt%) and O (1.4–13.3 wt%). According to Ti–Al and Ti–O binary phase diagrams [10], Ti–Al and Ti–O compounds may be formed. Wide center zone consists of three sub-layers and they are Ti, Cu (3.7–82 wt%) and Ti (18–96.3 wt%), and Cu. Based on Cu–Ti binary phase diagram, this layer maybe contain Cu–Ti compounds, Cu and α -Ti. Narrow black layer contains Ti and a small amount of Cu and Fe. Although the EPMA analysis of C was missing, this layer may be TiC. On the base of Ti–C binary phase diagram, Ti combines with C

Table 1

The chemical compositions and the thermo-physical properties of Ti and Cu.

Chemical compositions (wt. %)										
Material	H	C	O	N	Bi	S	Fe	Sb	As	Pb
Ti	0.015	0.10	0.25	0.05	—	—	0.30	—	—	—
Cu	—	—	—	—	0.001	0.005	0.005	0.002	0.002	0.005
Thermo-physical properties										
Material	Melting point (K)	Density at 293 K (g/cm^3)	Crystal structure ^a at 293 K			Coefficient of thermal expansion ($10^{-6}/\text{K}$) 293–373 K				Young's modulus (GPa)
Ti	1913–1943	4.5	h.c.p.			8.2				115
Cu	1338–1355	8.92	f.c.c.			16.92				125

^a h.c.p. = hexagonal-close-packed; f.c.c. = face-centerd-cubic.

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